

High Flow PC WONDERLITE® PC-175

Product Description: High Flow Polycarbonate

Properties	ISO Test Method	Test Condition	Unit	PC-175
Melt Flow Index	1133	300°C×1.2KG	ml/10 min	65
Mass Density	1183	23 °C	g/cm ³	1.2
Tensile Strength	527	50 mm/min, yield	MPa	60
		50 mm/min, break	MPa	50
Tensile Elongation	527	50 mm/min	%	65
Flexural Strength	178	2 mm/min	MPa	90
Flexural Modulus		2 mm/min	GPa	2.4
Izod Impact Strength	180/1A	23°C, Notched,3.2mm	KJ/m ²	8
		-30°C, Notched,3.2mm	KJ/m ²	-
Charpy Impact Strength	179	23°C, Notched,3.2mm	KJ/m ²	10
		-30°C, Notched,3.2mm	KJ/m ²	-
Vicat Softening Temp.	306	50°C/hr;1KG	°C	145
		50°C/hr;5KG	°C	140
Heat Distortion Temp.	75/A	1.8MPa, unannealed	°C	124
		1.8MPa, annealed	°C	140
Coefficient of Linear Thermal Expansion	11359	-	-	6.0~8.0x10 ⁻⁵
Flammability	-	UL-94	-	-
Mold Shrinkage	294-4	-	%	0.5~0.7
Symbol	1043	-	-	>PC<

September 23, 2025

Notes: The value provided herein has been established on above test methods and conditions, which only as reference for selecting material, NOT guaranteed values or formal specifications. There can be variation within normal tolerances in colors.

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